



# EXHIBITOR LIST

ESTREL CONGRESS CENTER, BERLIN

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|  |     |                                   |     |                                 |     |
|--|-----|-----------------------------------|-----|---------------------------------|-----|
| 3E Smart Solutions                         | U1  | FUJI CORPORATION                  | G5  | PROTAVIC / AFELIM               | B2  |
| ACI Materials                              | B9  | FUJIFILM Dimatix                  | C4  | PST Sensors                     | A6  |
| AFELIM                                     | B1  | Fujikura Kasei                    | U5  | Purdue SMART                    | T1  |
| AKONEER                                    | U6  | Global Inkjet Systems             | G7  | Quad Industries                 | E3  |
| Ames Goldsmith Corporation                 | A4  | Hamamatsu                         | F1  | Quantica                        | D12 |
| Arkema / AFELIM                            | B1  | Henkel                            | D2  | RISE                            | G4  |
| BeLink Solutions                           | A8  | HumminK / AFELIM                  | C1  | Roartis                         | D3  |
| BotFactory                                 | B6  | IDS                               | B7  | Saralon                         | D11 |
| Brilliant Matters                          | C2a | ImageXpert                        | D9  | SIJ Technology                  | T3  |
| C3 Nano                                    | R3  | INKATRONIC                        | G1a | Smooth & Sharp                  | S3  |
| Celanese Micromax™                         | B4  | InnovationLab                     | T2  | Space Foundry                   | U3  |
| Ceradrop - MGI Digital Technology / AFELIM | C2  | JOANNEUM RESEARCH                 | C7  | Sun Chemical                    | E8  |
| Chimet                                     | A10 | Kimoto                            | A7  | SunRay Scientific               | C3  |
| COATEMA Coating Machinery                  | E2  | Metafas                           | G0  | SUSS MicroTec                   | E7  |
| CondAlign                                  | E5  | Metalor                           | E6  | syenta                          | U4  |
| Conductive Technologies                    | D8  | Molex                             | E1  | Tapecon                         | S2  |
| CONTAG                                     | D4  | Nagase ChemteX                    | B5  | Teca-Print                      | D1  |
| Coveme                                     | A1  | National Research Council Canada  | G6  | TNO at Holst Centre             | B2a |
| Danish Technological Institute             | F2  | Neotech AMT                       | C5  | TracXon                         | E4  |
| DELO Industrial Adhesives                  | U2  | Notion Systems                    | A5  | Voltera                         | S1  |
| DoMicro                                    | C8  | nsm Norbert Schläfli              | D7  | VTT                             | C6  |
| Eastman Kodak Company                      | D6  | OrelTech                          | A2  | Warsaw University of Technology | G1  |
| ELANTAS                                    | B8  | Panacol-Elosol                    | F4  | Witte Technology                | R2  |
| Electroninks                               | A9  | Panasonic Electronic Materials    | G2  | XTPL                            | B3  |
| Encres DUBUIT                              | D5  | Printed Electronics Limited (PEL) | T3  |                                 |     |
| Fraunhofer IAP                             | A3  | Printed Energy                    | G8  |                                 |     |
| Fraunhofer IKTS                            | D0  | PrintUp Institute                 | G3  |                                 |     |